

# THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

Young et al.

Serial No.: 10/614,311

Filed: July 7, 2003

Title: AVANCED BI-DIRECTIONAL LINEAR POLISHING SYSTEM AND

**METHOD** 

Group Art Unit: Not yet assigned Examiner: Not yet assigned

Docket: NT-251C1-US

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the US Postal Service as Earst Class Mail

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Signed:

## **INFORMATION DISCLOSURE STATEMENT**

Commissioner for Patents P.O. BOX 1450 Alexandria, VA 22313-1450

Dear Sir:

Applicants submit information herewith to comply with the obligations set forth in 37 CFR §1.56. This submission is not an admission that any of the documents are prior art or otherwise relevant to the subject application.

This IDS is submitted:

- [] with a filed patent application or within 3 months of the US application filing date;
- [X] before the mailing of a first office action on the merits;
- [] after the first office action, but prior to a final rejection or notice of allowance, and is accompanied by the fee set forth in 37 CFR §1.17(p) or a certification set forth below; or
- [] after a final rejection or notice of allowance, and is accompanied by the fee set forth in 37 CFR §1.17(p) and a certification set forth below, where this submission is a petition requesting consideration of this IDS.

If identified above, Applicant certifies that:

[] the information was first cited in a communication from a foreign patent office in a counterpart foreign application less than 3 months prior to this IDS; or

[] to the knowledge of the person signing this certification after making reasonable inquiry, the information was not known to any individuals designated in 37 CFR §1.56 more than 3 months prior to this IDS.

If any matters can be resolved by telephone, Applicant requests that the Patent and Trademark Office call the Applicant at the telephone number listed below.

Respectfully submitted,

Reg. No. 35,547

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#### INFORMATION DISCLOSURE STATEMENT

#### **US PATENT DOCUMENTS**

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		EP 0 517 594	Dec., 1992	Baldy	In Serial No. 09/684,059
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Examiner	Date	
Signature	Considere	ed